**Invention Disclosure Form**

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| --- | --- | --- | --- |
| **Title of Invention** |  | **Type of Patents** | ☐ Invention ☐ Utility |
| **Applicant (s)** | Full name: Address: Post code: Nationality/ headquarter:(Note: please also provide the Chinese name & address if applicable) |
| **Inventor (s)** | Full name: Citizenship: (Note: please also provide the Chinese name & address if applicable) |
| **Priority if requested** | Priority date:Application No.:Country/region:DAS code: |
| **Requesting substantive examination (only for invention)** | □request it while filing□request it after receiving official notice |

1. **Field of technology**

(Note: the technical field the invention belongs to directly and specifically)

1. **Technical background**

(Note: Please list key prior art references ,e.g. patent, book, article, or thesis, and briefly describe the disadvantages thereof compared with this invention)

1. **Description of invention**

（1）The technical problem to be solved

（2）The technical solution used in the invention.

(Note: This is the most important part of this application, please completely disclose all the key points implementing the solution.)

（3）Advantages of the invention compared to the prior art.

(Note: Please also provide experimental data on cell, animal and clinic to prove the advantage if involved with chemical/biological field.**)**

1. **Drawings & brief description thereof**

(Note: Please briefly illustrate the **attached CAD drawing**, chemical structures, and flow charts of processes.)

1. **Specific embodiments**（Note: The embodiment may be one or more, which is the detailed solution of the invention, and provides additional technical features based on the key points to achieve better effects.）
2. **Replacement to this invention (optional)**

(Note: If there is replacement for this invention? If so, please also describe to extend the patent scope and avoid bypassing by competitors.)

1. **Other information that will benefit the understanding of the invention. (optional)**

(Note: please interpret the technical terms and abbreviation in English.)